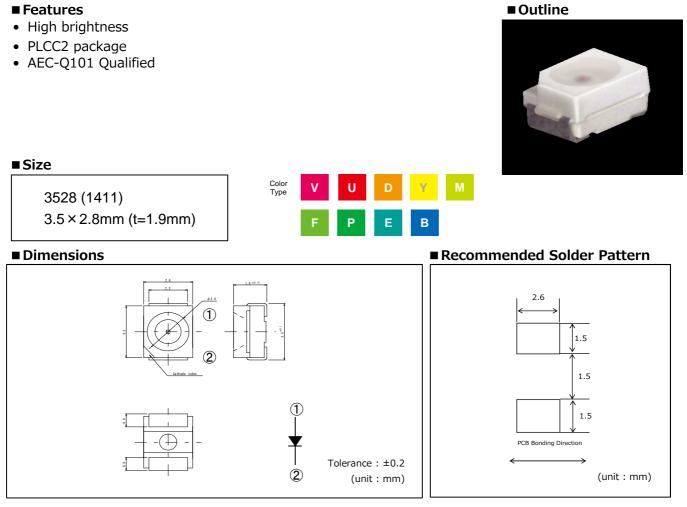


SML-Z14x(C) Series

Data Sheet



■ Moisture sensitivity level(MSL) : Level 3

Specifications

				Abso	olute Ma	ximum R	Ratings (Ta=25	°C)			Electr	ical and	d Optica	I Char	acteristi	cs (Ta=	=25ºC)		
Part No.	Chip Structure	Emitting	Power	Forward	Peak Forward	Reverse		Storage Temp.	Forward \	/oltage V _F	Reverse	Current I _R	Domir	nant W	aveleng	th λ _D	Lumino	ous Inte	ensity I _V
		Color	Dissipation	Current	Current	Voltage		0 1	Тур.	١ _F	Max.	V _R	Min.*2	Тур.	Max.*2	I _F	Min.	Тур.	I _F
			P _D (mW)	I _F (mA)	I _{FP} (mA)	$V_{R}(V)$	T _{opr} (°C)	T _{stg} (°C)	(V)	(mA)	(µA)	(V)	(nm)	(nm)	(nm)	(mA)	(mcd)	(mcd)	(mA)
SML-Z14VT(C)		Red											625	630	635		56	112	
SML-Z14UT(C)		Reu	168						1.9				615	620	625		112	224	
SML-Z14DT(C)		Orange											602	605	608		140	280	
SML-Z14YT(C)	AlGaInP	Yellow	w	70	0 200*1	¹ 12				1		12	586	589	592		140	200	
SML-Z14MT(C)		Yellowish Green	175				-40 ~ +100	-40 ~ +100	2.0	20	10		568	571	574	20	45	90	20
SML-Z14FT(C)		Green	175						2.0				561.5	564	566.5		22.4	45	
SML-Z14PT(C)		Green											557	560	563		11.2	22.4	1
SMLZ14EGT(C)	InGaN	Green	120	20	400*1	5			3.4			5	519	528	536		710	1100	1
SMLZ14BGT(C)	moan	Blue	114	30	100*1	э			3.3			5	464	470	476		140	280]

*1 : 1/10,1kHz *2 : Measurement tolerance:±1nm

Electrical Characteristics Curves

Reference

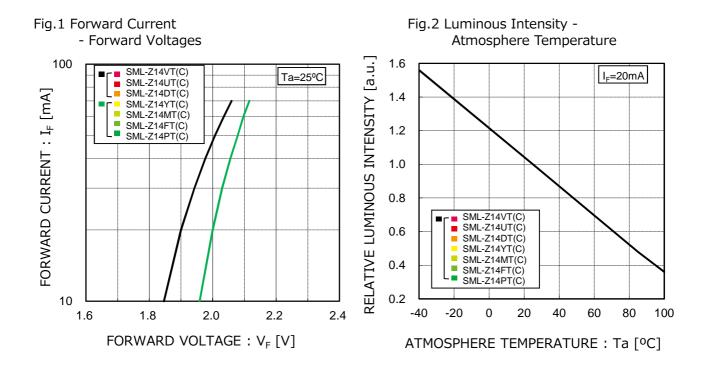
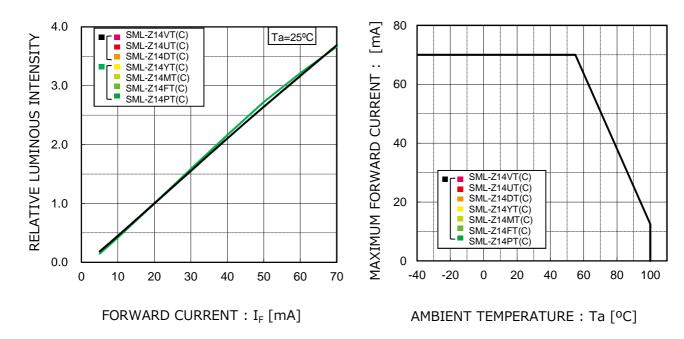


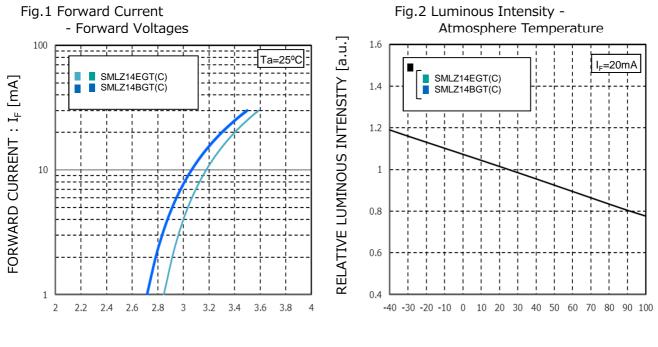
Fig.3 Luminous Intensity - Forward Current





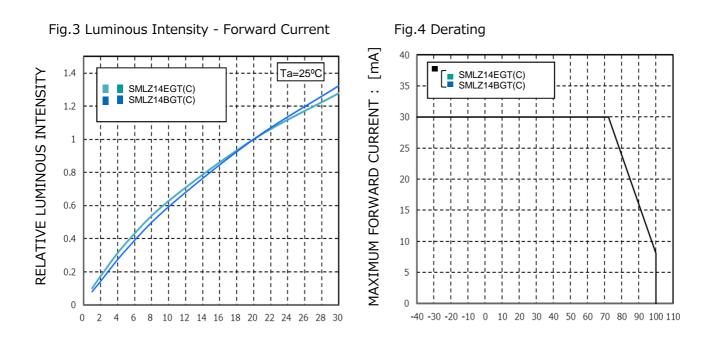
■ Electrical Characteristics Curves

Reference



FORWARD VOLTAGE : V_F [V]





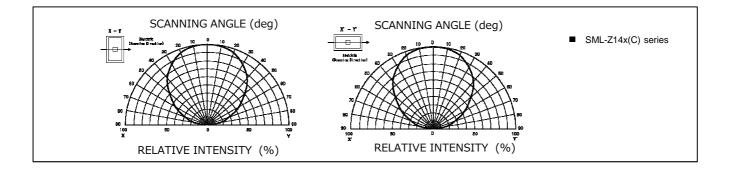
FORWARD CURRENT : I_F [mA]

AMBIENT TEMPERATURE : Ta [°C]

■ Viewing Angle

[Data Sheet]

Reference



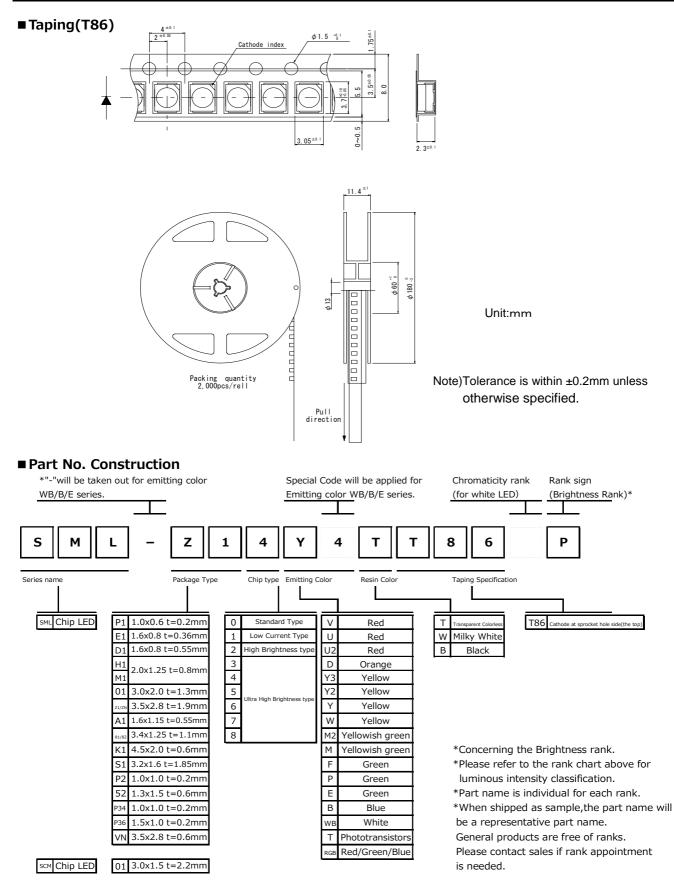
SMLZ14BGT(C)

■ Rank Reference of Brightness*

*Measurement tolerance:±10%

Red(V,U))															(Ta	=25°C, I _F	=20mA)
Rank	AM	AN	AP	AQ	AR	AS	AT	AU	AV	AW	AX	AY	AZ	BA	BB	BC	BD	BE
lv (mcd)	28~35.5	35.5~45	45~56	56~71	71~90	90~112	112~140	140~180	180~224	224~280	280~355	355~450	450~560	560~710	710~900	900~1120	1120~1400	1400~180
SML-Z14VT(C))																	
SML-Z14UT(C)																		
Orange([D)															(Ta	=25ºC, I _F	=20mA
Rank	AM	AN	AP	AQ	AR	AS	AT	AU	AV	AW	AX	AY	AZ	BA	BB	BC	BD	BE
lv (mcd)	28~35.5	35.5~45	45~56	56~71	71~90	90~112	112~140	140~180	180~224	224~280	280~355	355~450	450~560	560~710	710~900	900~1120	1120~1400	1400~180
SML-Z14DT(C)																		
Yellow(Y)															(Ta	=25ºC, I _F	=20mA
Rank	AM	AN	AP	AQ	AR	AS	AT	AU	AV	AW	AX	AY	AZ	BA	BB	BC	BD	BE
	-											055 150	450 500	FCO 740	710 000	900~1120	4400 4400	1400~180
Iv (mcd)		35.5~45	45~56	56~71	71~90	90~112	112~140	140~180	180~224	224~280	280~355	355~450	450~560	560~710	710~900	900~1120	1120~1400	1400-0100
lv (mcd) SML-Z14YT(C)		35.5~45	45~56	56~71	71~90	90~112	112~140	140~180	180~224	224~280	280~355	355~450	450~560	560~710	710~900	900~1120	1120~1400	1400-4 100
SML-Z14YT(C)						90~112	112~140	140~180	180~224	224~280	280~355	355~450	450~560	560~710	710~900		=25°C, I _F	
SML-Z14YT(C)						90~112 AM	112~140 AN	140~180 AP	180~224 AQ	224~280 AR	280~355 AS	355~450 AT	450~560 AU	AV	AW			
sml-z14yt(c) Yellowish	n Gre	en/Gi	reen(_{AJ}	М,Р ,І АК	F)	AM	AN	AP	AQ	AR	AS		AU	AV	AW	(Ta AX	=25ºC, I _F AY	=20mA AZ
SML-Z14YT(C) Yellowish Rank Iv (mcd)	AG 9~11.2	en/Gi	reen(_{AJ}	М,Р ,І АК	F)	AM	AN	AP	AQ	AR	AS	AT	AU	AV	AW	(Ta AX	=25ºC, I _F AY	=20mA AZ
SML-Z14YT(C) Yellowish Rank Iv (mcd) SML-Z14MT(C) SML-Z14PT(C)	AG 9~11.2	en/Gi	reen(_{AJ}	М,Р ,І АК	F)	AM	AN	AP	AQ	AR	AS	AT	AU	AV	AW	(Ta AX	=25ºC, I _F AY	=20mA AZ
SML-Z14YT(C) Yellowish Rank Iv (mcd) SML-Z14MT(C) SML-Z14PT(C)	AG 9~11.2	en/Gi	reen(_{AJ}	М,Р ,І АК	F)	AM	AN	AP	AQ	AR	AS	AT	AU	AV	AW	(Ta AX	=25ºC, I _F AY	=20mA AZ
SML-Z14YT(C) Yellowish Rank	AG 9~11.2	en/Gi	reen(_{AJ}	М,Р ,І АК	F)	AM	AN	AP	AQ	AR	AS	AT	AU	AV 180~224	AW	(Ta AX 280~355	=25ºC, I _F AY	=20mA AZ
SML-Z14YT(C) Yellowish Rank Iv (mcd) SML-Z14MT(C) SML-Z14PT(C) SML-Z14FT(C)	AG 9~11.2	en/Gi	reen(_{AJ}	М,Р ,І АК	F)	AM	AN	AP	AQ	AR	AS	AT	AU	AV 180~224	AW 224~280	(Ta AX 280~355	=25ºC, I _F AY	=20mA AZ
SML-Z14YT(C) Yellowish Rank Iv (mcd) SML-Z14MT(C) SML-Z14PT(C) SML-Z14FT(C) Green(E)	AG 9~11.2	en/Gi AH 11.2~14	reen(AJ 14~18	M,P,I AK 18~22.4	F) AL 22.4~ 28	AM 28~35.5	AN 35.5~45 V1	AP 45~56	AQ 56~71 W1	AR 71~90	AS 90~112	AT 112~140 	AU 140~180	AV 180~224 (Ta: Y2	AW 224~280 =25°C, I⊧	(Ta AX 280~355 =20mA) Z2	=25ºC, I _F AY	=20mA AZ
SML-Z14YT(C) Yellowish Rank Iv (mcd) SML-Z14MT(C) SML-Z14PT(C) SML-Z14FT(C) Green(E) Rank	AG 9~11.2 9~11.2	en/Gi AH 11.2~14	reen(AJ 14~18	M,P,I AK 18~22.4	F) AL 22.4~ 28	AM 28~35.5	AN 35.5~45 V1	AP 45~56	AQ 56~71 W1	AR 71~90	AS 90~112	AT 112~140 	AU 140~180 Y1	AV 180~224 (Ta: Y2	AW 224~280 =25°C, I _F Z1	(Ta AX 280~355 =20mA) Z2	=25ºC, I _F AY	=20mA AZ
SML-Z14YT(C) Yellowish Rank Iv (mcd) SML-Z14MT(C) SML-Z14PT(C) SML-Z14FT(C) Green(E) Rank Iv (mcd) SMLZ14EGT(C)	AG 9~11.2 9~11.2	en/Gi AH 11.2~14	reen(AJ 14~18	M,P,I AK 18~22.4	F) AL 22.4~ 28	AM 28~35.5	AN 35.5~45 V1	AP 45~56	AQ 56~71 W1	AR 71~90	AS 90~112	AT 112~140 	AU 140~180 Y1	AV 180~224 (Ta: Y2 1800~2200	AW 224~280 =25°C, I _F Z1	(Ta AX 280~355 =20mA) Z2 2800~3600	=25ºC, I _F AY	=20mA AZ
SML-Z14YT(C) Rank Iv (mcd) SML-Z14MT(C) SML-Z14PT(C) SML-Z14FT(C) Green(E) Rank Iv (mcd)	AG 9~11.2 9~11.2	en/Gi AH 11.2~14	reen(AJ 14~18	M,P,I AK 18~22.4	F) AL 22.4~ 28	AM 28~35.5	AN 35.5~45 V1	AP 45~56	AQ 56~71 W1	AR 71~90	AS 90~112	AT 112~140 	AU 140~180 Y1	AV 180~224 (Ta: Y2 1800~2200	AW 224~280 =25°C, I _F Z1 2200~2800	(Ta AX 280~355 =20mA) Z2 2800~3600	=25ºC, I _F AY	=20mA AZ

*Please note that the brightness of some products may fall between ranks (half rank).



Packing Specification

Complying with IPC/JEDEC J-STD-033.

Precaution (Surface Mount Device)

1. Storage

If the product is heated during the reflow under the condition of hygroscopic state,

it may vaporize and expand which will influence the performance of the product.

Therefore, the package is waterproof. Please use the product following the conditions:

•Using Conditions

Classification	Temperature	Humidity	Expiration Date	Remark
①Before using	5~30℃	30~70%RH	Within 1 year from Receiving	Storage with waterproof package
②After opening package	5~30℃	Below 70%RH	Within 168h	Please storing in the airtight container with our desiccant (silica gel)

Baking

Bake the product in case of below:①The expiration date is passed.②The color of 5% and 10% on humidity indicator card is not green.

(Even if the product is before expiration date.)

Baking Conditions

Tempera	iture	Time	Humidity
60±3°	С С	40~48h	Below 20%RH
Remark	•Reel and so please	ducts in reel. embossed tape try not to apply end bake once.	are easy to be deformed when baking, stress on it.

2. Application Methods

2 – 1. Precaution for Drive System and Off Mode

Design the circuit without the electric load exceeding the ABSOLUTE MAXIMUM RATING that applies on the products. If drive by constant voltage, it may cause current deviation of the LED and result in deviation of luminous intensity, so we recommend to drive by constant current.

(Deviation of VF Value will cause deviation of current in LED.) Furthermore, for off mode, please do not apply voltage neither forward nor reverse. Especially, for the products with the Ag-paste used in the die bonding, there's high possibility to cause electro migration and result in function failure.

2 – 2. About Derating

It is considered that derating characteristics will not result in LED chip's electrical destruction. Even within the derating, the reliability and luminous life can be affected depending on operating conditions and ambient environment. So we would be appreciate it if you can confirm with your application again.

2 – 3. About product life

Depending on operating conditions and environment(applied current, ambient temperature and humidity, corrosive gas), decreasing of luminosity and change of chromaticity may occur even within the specification conditions.

Please contact our sales office if you use it for the following applications.

1)It requires long luminosity life

②It is always lit

2 – 4. Applied Stress on Product

The top of the LED is very soft, which the silicon resin is used as sealing resin.

Therefore, please pay attention to the overstress on it which may influence its reliability.

<u>2 – 5. Usage</u>

The Product is LED. We are not responsible for the usage as the diode such as Protection Chip, Rectifier, Switching and so on.

3. Others

3 – 1. Surrounding Gas

Notice that if it is stored under the condition of acid gas (chlorine gas, sulfured gas) or alkali gas (ammonia), it may result in low soldering ability (caused by the change in quality of the plating surface) or optical characteristics changes (light intensity, chrominance) and change in quality of cause die bonding (Ag-paste) materials. All of the above will function failure of the products.

Therefore, please pay attention to the storage environment for mounted product (concern the generated gas of the surrounding parts of the products and the atmospheric environment).

<u>3 – 2. Electrostatic Damage</u>

The product is part of semiconductor and electrostatic sensitive, there's high possibility to be damaged by the electrostatic discharge. Please take appropriate measures to avoid the static electricity from human body and earthing of production equipment. Especially, InGaN type LEDs have lower resistance value of electrostatic discharge and it is recommended to introduce the ESD protection circuit. The resistance values of electrostatic discharge (actual values) vary with products, therefore, please call our Sales staffs for inquiries.

3-3. Electromagnetic Wave

Applications with strong electromagnetic wave such as, IH cooker, will influence the reliability of LED, therefore please evaluate before using it.

4. Mounting

4 – 1. Soldering

•No resin hardening agent such as filler is used in the sealing resin of the product. Therefore, resin expansion and moisture absorption at humidity will cause heat stress during soldering process and finally has bad influence on the product's reliability.

•The product is not guaranteed for flow soldering.

•Do not expose the product in the environment of high temperature (over 100°C) or rapid temperature shift (within 3°C/sec. of temperature gradient) during the flow soldering of surrounding parts. In case of carrying out flow soldering of surrounding parts without recommended conditions, please contact us for inquiries.

•Please set appropriate reflow temperature based on our product usage conditions and specification.

•The max for reflowing is 2 times, please finish the second reflow soldering and flow soldering with other parts within the usage limitation after open the moistureproof package.

•Compare with N2 reflow, during air reflow, because of the heat and surrounding conditions, it may cause the discoloration of the resin.

•For our product that has no solder resist, because of its solder amount and soldering conditions, one of its specific characteristics is that solder will penetrate into LED. Thus, there's high possibility that will influence its reliability.Therefore, please be informed, concerning it before using it.

4 – 2. Automatic Mounting

4-2-1. Suction nozzle

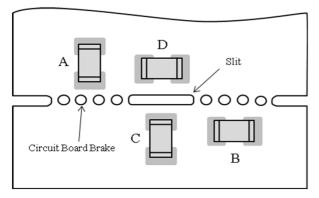
Excessive load may cause damage inside the LED product, so select an optimal suction nozzle according to the material and shape of the LED product.

4-2-2. Mini Package (Smaller than 1608 size)

•Vibration may result in low mounting rate since it will cause the static electricity of product and adhere to top cover tape. Therefore, the magnet should be set on parts feeder cassette of the mounter to control the product stabilization. In addition, it is recommended to set ionizer to prevent electrostatic charge.

4 – 3. Mounting Location

The stress like bending stress of circuit board dividing after mounting, may cause LED package crack or damage of LED internal junction, therefore, please concern the mounting direction and position to avoid bending or screwing with great stress of the circuit board.



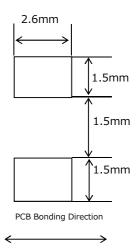
Stress strength according to he mounting position: A > B > C > D

4-4. Mechanical Stress after Mounting

The mechanical stress may damage the LED after Circuit Mounting, so please pay attention to the touch on product.

4 – 5. Soldering Pattern for Recommendation

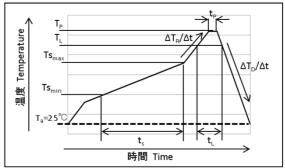
We recommend the soldering pattern that shows on the right. It will be different according to mounting situation of circuit board, therefore, please concern before designing.



4 – 6. Reflow Profile

For reflow profile, please refer to the conditions below:(※) ■Meaning of marks. Conditions

	or marks, conditions	
Mark	Meanings	Conditions
Ts _{max}	Maximum of pre-heating temperature	180°C
Ts _{min}	Minimum of pre-heating temperature	140°C
t _s	Time from Tsmin to Tsmax	Over 60sec.
Τ _L	Reference temperature	230~250℃
t_L	Retention time for TL	Within 40sec.
Τ _Ρ	Peak temperature	250℃(Max)
t _P	Time for peak temperature	Within 10sec.
ΔT _R /Δt	Temperature rising rate	Under 3℃/sec.
ΔT _D /Δt	Temperature decreasing rate	Over -3℃/sec.



*Above conditions are for reference. Therefore, evaluate by customer's own circuit boards and reflow furnaces before using, because stress from circuit boards and temperature variations of reflow furnaces vary by customer's own conditions.

4 – 7. Attention Points in Soldering Operation

This product was developed as a surface mount LED especially suitable for reflow soldering. So reflow soldering is recommended. In case of implementing manual soldering,

please take care of following points.

1SOLDER USED

Sn-Cu, Sn-Ag-Cu, Sn-Ag-Bi-Cu

②HAND SOLDERING CONDITION

LED products do not contain reinforcement material such as a glass fillers.

So thermal stress by soldering greatly influence its reliability.

Please keep following points for manual soldering.

	ITEM	RECOMMENDED CONDITION]
a)	Heating method	Condition) Temp. of iron top less than 325℃ within 3 sec.	Fig-1 SOLDERING IRON
a)		Heating on PCB pattern, not direct to the LED. (Fig-1)	/
b)	Handling after	Please handle after the part temp.	¥ ×
0)	soldering	goes down to room temp.	

4 – 8. Cleaning after Soldering

Please follow the conditions below if the cleaning is necessary after soldering.

Solvent	We recommend to use alcohols solvent such as, isopropyl alcohols
Temperature	Under 30℃ within 3 minutes
Ultrasonic Cleaning	15W/Below 1 liter (capacity of tank)
Drying	Under 100℃ within 3 minutes

SOLDERING LAND

	Notes
1)	The information contained herein is subject to change without notice.
2)	Before you use our Products, please contact our sales representative and verify the latest specifica- tions :
3)	Although ROHM is continuously working to improve product reliability and quality, semicon- ductors can break down and malfunction due to various factors. Therefore, in order to prevent personal injury or fire arising from failure, please take safety measures such as complying with the derating characteristics, implementing redundant and fire prevention designs, and utilizing backups and fail-safe procedures. ROHM shall have no responsibility for any damages arising out of the use of our Poducts beyond the rating specified by ROHM.
4)	Examples of application circuits, circuit constants and any other information contained herein are provided only to illustrate the standard usage and operations of the Products. The periphera conditions must be taken into account when designing circuits for mass production.
5)	The technical information specified herein is intended only to show the typical functions of and examples of application circuits for the Products. ROHM does not grant you, explicitly or implicitly any license to use or exercise intellectual property or other rights held by ROHM or any other parties. ROHM shall have no responsibility whatsoever for any dispute arising out of the use or such technical information.
6)	The Products specified in this document are not designed to be radiation tolerant.
7)	For use of our Products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a ROHM representative : transportation equipment (i.e cars, ships, trains), primary communication equipment, traffic lights, fire/crime prevention, safety equipment, medical systems, servers, solar cells, and power transmission systems.
8)	Do not use our Products in applications requiring extremely high reliability, such as aerospace equipment, nuclear power control systems, and submarine repeaters.
9)	ROHM shall have no responsibility for any damages or injury arising from non-compliance with the recommended usage conditions and specifications contained herein.
10)	ROHM has used reasonable care to ensur the accuracy of the information contained in this document. However, ROHM does not warrants that such information is error-free, and ROHM shall have no responsibility for any damages arising from any inaccuracy or misprint of such information.
11)	Please use the Products in accordance with any applicable environmental laws and regulations such as the RoHS Directive. For more details, including RoHS compatibility, please contact a ROHM sales office. ROHM shall have no responsibility for any damages or losses resulting non-compliance with any applicable laws or regulations.
12)	When providing our Products and technologies contained in this document to other countries you must abide by the procedures and provisions stipulated in all applicable export laws and regulations, including without limitation the US Export Administration Regulations and the Foreign Exchange and Foreign Trade Act.
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